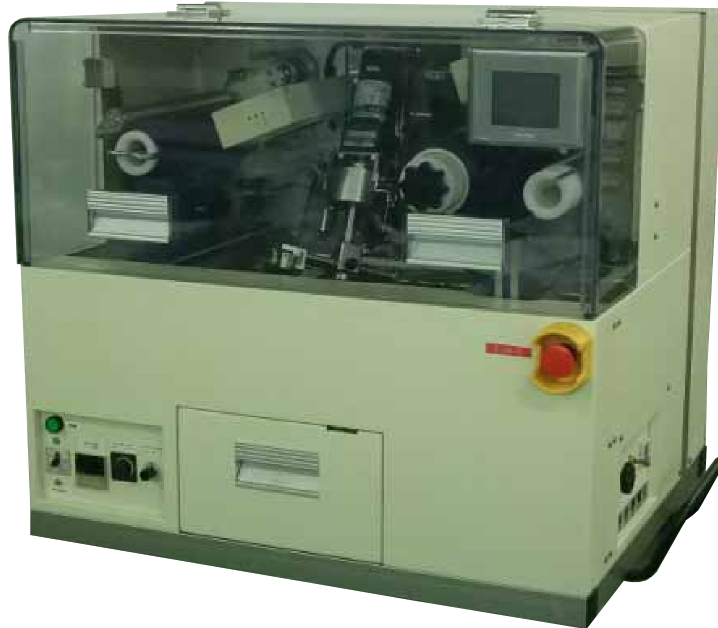
SEMI AUTOMATIC WAFER MOUNTER FOR DICING PROCESS
NEL-MSA840-II



• Applicable wafer size	4”, 5“, 6”, 8“
• Applicable frame size	for 6”, for 8”
• Through-put	approx. 30 sec/wafer (excluding wafer and frame setting time and wafer mount frame removing time)
• Dimension	(W)800x(D)670x(H)750(mm)
• Weight	approx. 135kgf

- Semi automatic type to set wafer and frame manually and to do tape applying, cutting and removing waste tape automatically
- ”Non contact chuck method” to contact 3~4mm wafer edge (Contact chuck method also applicable)
- 1 Fan type and 2 brush type ionizer equipped
- Easy connecting to Fully auto wafer and dicing frame handling tool for transforming to Fully automatic system.

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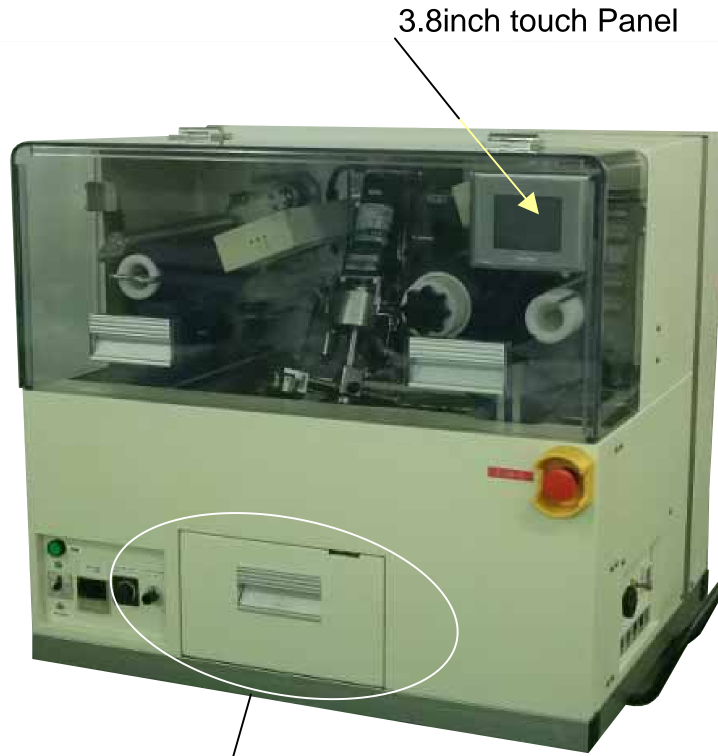
3.8inch touch Panel



Simple face

Drawing out / in by hand with air cylinder assist.

Primary function	
Work holding system	By vacuuming
Wafer table	Non contact table available
Static eliminator	1 Fan type & 2 brush type equipped
Taping speed control	Variable by manual setting
Taping tension	H/L auto changing with tape Dia. H/L Variable by manual setting
Tape remaining	Detecting sensor equipped.
Cut number counter	Equipped
No wafer operation(*)	Available.

Optional function	
Work holding system	Magnetic holder can be added in case of using high adhesive tape.
Taping speed control	Put number through touch panel. The number can be embedded in recipe
Taping tension	Put number through touch panel. The number can be embedded in recipe
Cutting miss detection	Available
Cutting Dia. detection	Available

(*) No wafer operation; Tape applying on dicing frame without wafer.

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